



Connectors > PCB Connectors > SAS & MiniSAS > PT30 XFP Connectors



SAS Connector Type: **SAS**

Connector & Housing Type: **Receptacle**

Connector System: **Wire-to-Board**

Number of Positions: **29**

Number of Rows: **1**

[All PT30 XFP Connectors \(2\)](#)

Features

Product Type Features

Connector & Contact Terminates To	Printed Circuit Board
Shell	Without
SAS Connector Type	SAS
Connector & Housing Type	Receptacle
Connector System	Wire-to-Board

Configuration Features

Number of Positions	29
Number of Rows	1
Number of Ports	1
PCB Mount Orientation	Vertical

Body Features

Primary Product Color	Black
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Contact Features

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Contact Mating Area Plating Material	Gold (Au)
Contact Base Material	Copper Alloy
	30 µin
Contact Current Rating (Max)	1.5 A

Termination Features

Termination Method to PCB	Through Hole - Press-Fit
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Mechanical Attachment

PCB Mount Retention Type	Boardlock
PCB Mount Retention	With
Connector Mounting Type	Board Mount

Housing Features

Housing Material	Thermoplastic
Centerline (Pitch)	1.27 mm[.049 in]

Dimensions

Profile Height from PCB	9.15 mm[.36 in]
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Usage Conditions

High Temperature Housing	Yes
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Operation/Application

Circuit Application	Power & Signal
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Industry Standards

UL Flammability Rating	UL 94V-0
PCIe/SAS Generation	Gen2

Packaging Features

Packaging Method	Box & Tray, Tray
Packaging Quantity	540

Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	



Current ECHA Candidate List: JAN 2025 (247)  
Candidate List Declared Against: JUNE 2023 (235)  
Does not contain REACH SVHC

Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Not applicable for solder process capability

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Customers Also Bought



Documents

Product Drawings  
SAS BACKPLANE RECEPT, VERTICAL  
English

CAD Files  
Customer View Model  
ENG\_CVM\_CVM\_1735368-1\_C.2d\_dxf.zip  
English  
3D PDF  
3D  
Customer View Model  
ENG\_CVM\_CVM\_1735368-1\_C.3d\_igs.zip



English

Customer View Model

[ENG\\_CVM\\_CVM\\_1735368-1\\_C.3d\\_stp.zip](#)

English

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Product Specifications

[Product Specification](#)

English